



ORIENT DISPLAY

MAKE THINGS POSSIBLE

Specification for TFT

AFY800480A1-5.0INTH-R

Revision A



A	Orient Display
FY	TFT Type
800480	Resolution 800 x 480
A1	Serial A1
5.0	5.0", Module Dimension 120.70 x 75.80 x 3.95 mm
I	IPS Display
N	Top: -20~+70°C; Tstr: -30~+80°C
T	Transmissive
H	High Brightness, 800cd/m ²
R	Resistive Touch Panel
/	ST72568 OR COMPATIBLE
/	RGB 24bit interface



REVISION RECORD

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1. GENERAL INFORMATION

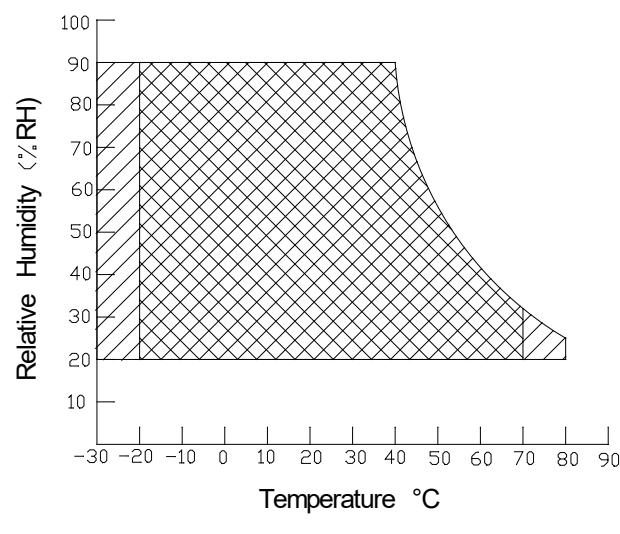
No.	Item	Contents	Unit
1	LCD size	5.0 inch (Diagonal)	/
2	Display mode	IPS/NORMALLY BLACK/Transmissive	/
3	Viewing direction(eye)	FREE	/
4	Gray scale inversion direction	-	/
5	Resolution(H*V)	800 *480 Pixels	/
6	Module size (L*W*H)	120.70*75.80*3.95	mm
7	Active area (L*W)	108.00*64.80	mm
8	Pixel pitch (L*W)	0.135*0.135	mm
9	Interface type	RGB 24bit interface	/
10	Color Depth	16.7M	/
11	Module power consumption	TBD(Appr)	W
12	Back light type	EDGE&WHITE LED	/
13	Driver IC	ST72568 OR COMPATIBLE	/
14	Weight	TBD(Appr)	G

2. ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min.	Max.	Unit	Note
Power supply input voltage for TFT	VDD	-0.3	4.0	V	
Backlight current (normal temp.)	ILED	-	100	mA	
Operation temperature	Top	-20	+70	°C	Note1
Storage temperature	Tst	-30	+80	°C	Note1
Humidity	RH	20%	90%	RH	Note1

Note1 :

- 1).The relative humidity and temperature range are as below sketch,90%RH Max.
- 2).The maximum wet bulb temperature $\leq 40^{\circ}\text{C}$ and without dewing.



3. ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS(at Ta=25°C)

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Power supply input voltage	VDD	3.1	3.3	3.6	V	
I/O logic voltage	VDDIO	-	-	-	V	
Input voltage 'H' level	VIH	0.7VDD	-	VDD	V	
Input voltage 'L' level	VIL	VSS	-	0.3VDD	V	
Power supply current	IVDD	-	30	-	mA	
TFT gate on voltage	VGH	-	-	-	V	
TFT gate off voltage	VGL	-	-	-	V	
Analog power supply voltage	AVDD	-	-	-	V	
TFT common electrode voltage	VCOM	-	-	-	V	Note1

Note1 : The value is just the reference value. VCOM must be adjusted to optimize display quality, as Crosstalk and Contrast Ratio etc..

4. BACKLIGHT CHARACTERISTICS

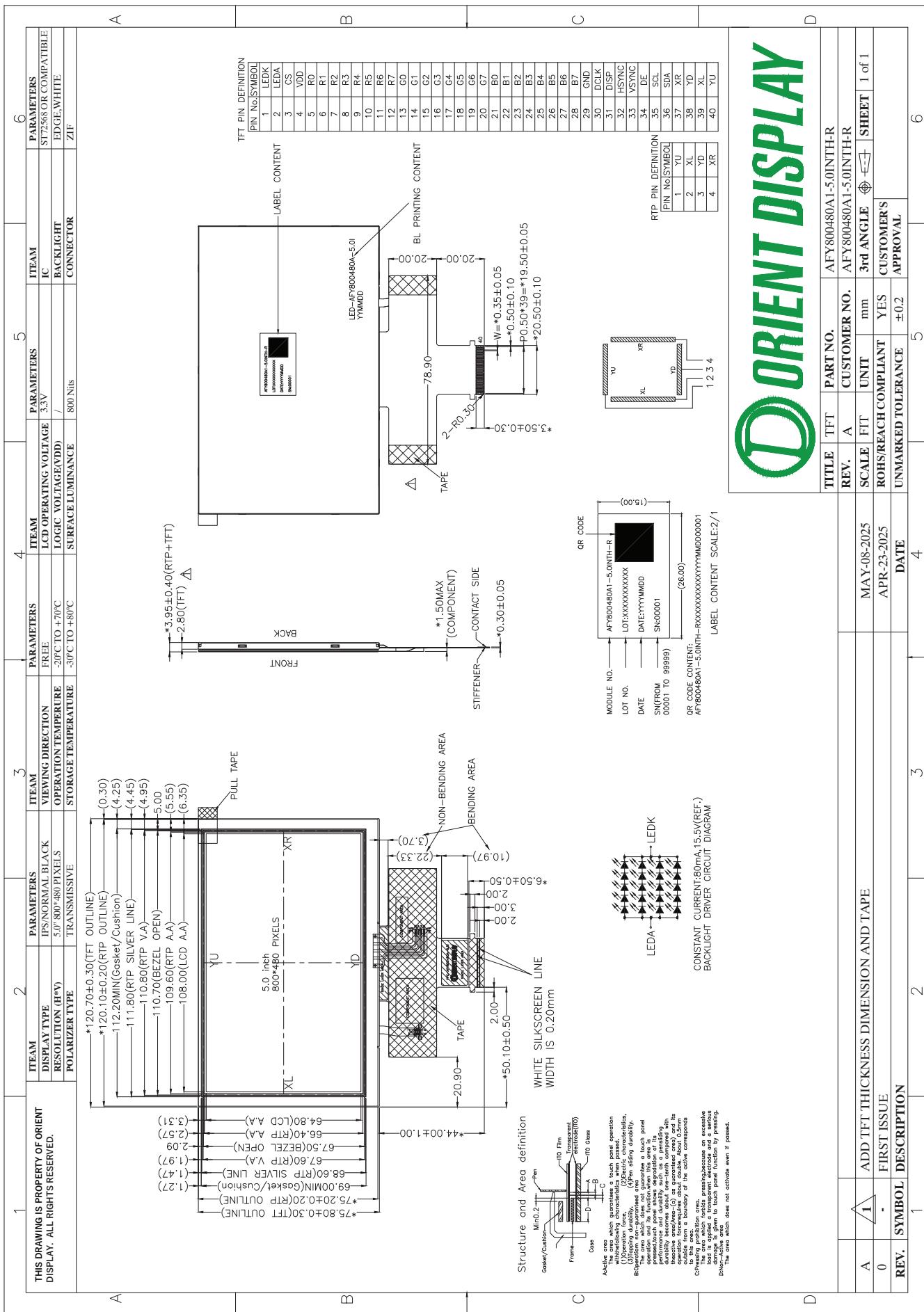
(at Ta=25°C,RH=60%)

Item	Symbol	Min.	Typ.	Max.	Unit	Note
LED forward voltage	VF	13.5	15.5	16.5	V	
LED forward current	IF	-	80	-	mA	IF=20*4mA
LED power consumption	PLED	-	U*I	-	W	Note1
Number of LED	-		20		PCS	
Connection mode	-	5	in series	4 in parallel	/	
LED life-time	-	20000	-	-	Hrs	Note2

Note1 : Calculator value for reference : $IF \cdot VF = PLED$

Note2 : The LED life-time define as the estimated time to 50% degradation of initial brightness at Ta=25°C and IF =80mA. The LED lifetime could be decreased if operating IF is larger than 80mA.

5. EXTERNAL DIMENSIONS



6. ELECTRO - OPTICAL CHARACTERISTICS

(Measuring in dark room, Backlight current IF=80mA, TFT VDD=3.3V, at 25±2°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark	Note
Response time	Tr+ Tf	-	-	30	40	ms	FIG.1	Note 1
Contrast ratio	Cr		800	960	-	-	FIG.2	Note 2
Surface luminance	Lv	θ=0°	600	800	-	cd/m ²	FIG.2	Note 3
Luminance uniformity	Yu	θ=0°	75	80	-	%	FIG.2	Note 4
NTSC	-	θ=0°	-	55	-	%	FIG.2	Note 5
Viewing angle	θ	∅=90°	70	80	-	deg	FIG.3	Note 6
		∅=270°	70	80	-	deg	FIG.3	
		∅=0°	70	80	-	deg	FIG.3	
		∅=180°	70	80	-	deg	FIG.3	
CIE (x,y) chromaticity	Red x	θ=0° ∅=0° Ta=25°C	Typ -0.04	TBD	Typ +0.04	-	FIG.2 CIE1931	Note 5
	Red y			TBD		-		
	Green x			TBD		-		
	Green y			TBD		-		
	Blue x			TBD		-		
	Blue y			TBD		-		
	White x			TBD		-		
	White y			TBD		-		

The TFT module should be stabilized at a given temperature for 10 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 10 minutes in a windless room.

Note1. Definition of response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state.

Normally white:Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.

Normally black:Rise time (T_{ON}) is the time between photo detector output intensity changed from 10% to 90%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 90% to 10%.

For additional information see FIG1.

Note2. Definition of contrast ratio

Contrast ratio(Cr) is defined mathematically by the following formula.

For more information see FIG.2.

Contrast ratio= $\frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$

Measured at the center area of the LCD

Note3. Definition of surface luminance

Surface luminance is the luminance with all pixels displaying white.

For more information see FIG.2.

Lv = Average Surface Luminance with all white pixels(P1,P2,P3, ,Pn)

Note4. Definition of luminance uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.2.

Yu = $\frac{\text{Minimum surface luminance with all white pixels (P1,P2,P3,.....,Pn)}}{\text{Maximum surface luminance with all white pixels (P1,P2,P3,.....,Pn)}}$

Note5. Definition of color chromaticity (CIE1931)

CIE (x,y) chromaticity, The x,y value is determined by screen active area center position. For more information see FIG.2.

Note6. Definition of viewing angle

Viewing angle is the angle at which the contrast ratio is greater than 10 angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the display surface. For more information see FIG.3.

For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope or

DMS series Instruments or compatible. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on CS-2000/BM-7 photo detector or compatible.

FIG.1. The definition of response Time

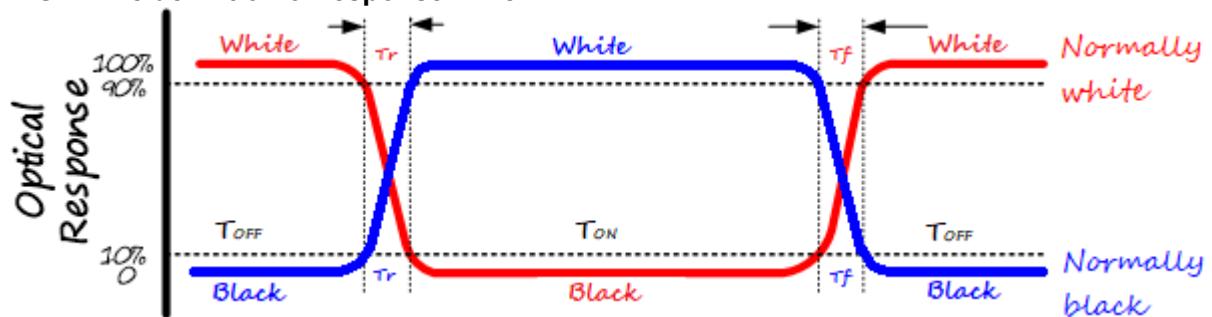


FIG.2. Measuring method for contrast ratio, surface luminance, luminance uniformity, CIE (x,y) chromaticity

H,V : Active area

Light spot size $\varnothing=1.5\text{mm}$ or $\varnothing=7.7\text{mm}$ (CS-2000/BM-7) 50cm distance or compatible distance from the LCM surface to detector lens.

Test spot position : see Figure a.

measurement instrument : Luminance meter CS-2000/BM-7 or compatible ,see Figure b.

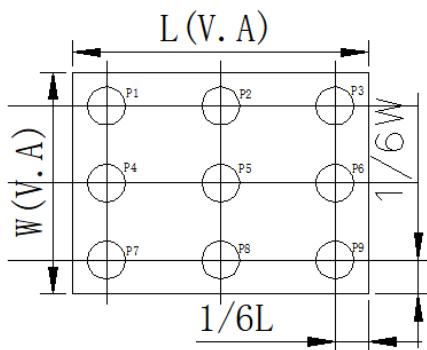


Figure a

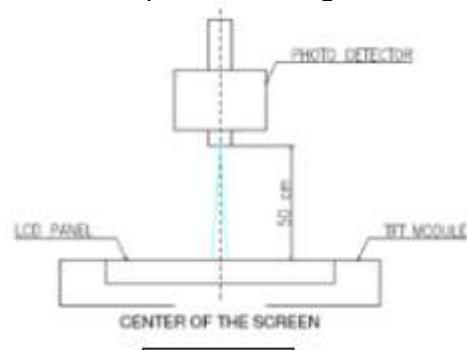
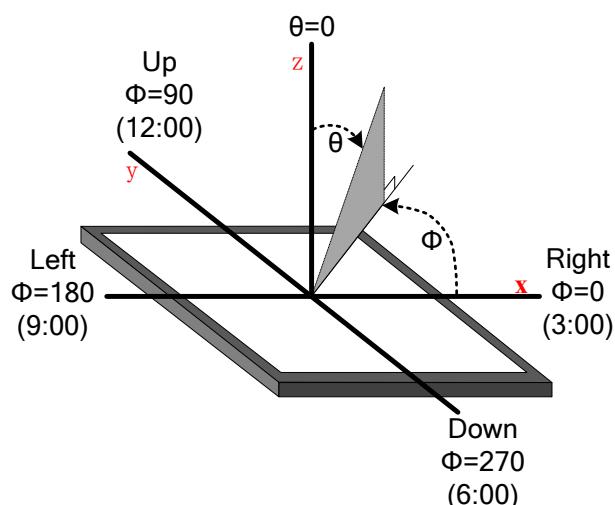


Figure b

FIG.3. The definition of viewing angle



7. INTERFACE DESCRIPTION

Module Interface description

Interface No.	Name	I/O or connect to	Description
1	LEDK	P	Power for LED backlight(Cathode)
2	LEDA	P	Power for LED backlight(Anode)
3	CS	I	Serial communication chip selection.
4	VDD	P	Power for LCD
5-12	Red(0-7)	I	Red data
13-20	Green(0-7)	I	Green data
21-28	Blue(0-7)	I	Blue data
29	GND	I	Ground
30	DCLK	I	Dot clock
31	DISP	I	Display on/off
32	H SYNC	I	Horizontal sync input.
33	V SYNC	I	Vertical sync input
34	DE	I	Data enable
35	SCL	I	Serial communication clock input.
36	SDA	I/O	Serial communication data input and output.
37	XR	I	X-Right
38	YD	I	Y-Down
39	XL	I	X-Left
40	YU	I	Y-Up

Remark :

1、For“I/O”，I: input, O: output, P: Power,NC or / : No connection/

2、The TFT module display as the picture below

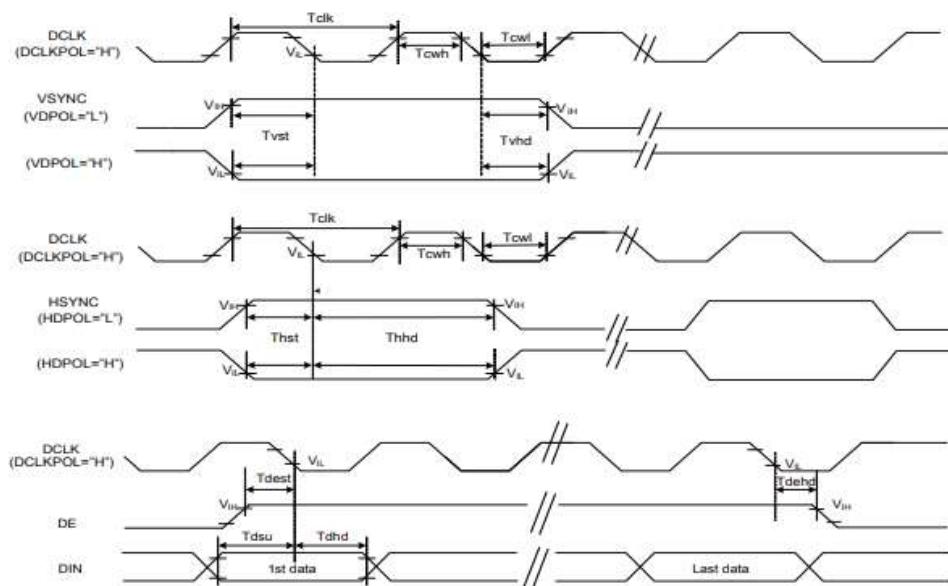


8.AC CHARACTERISTICS

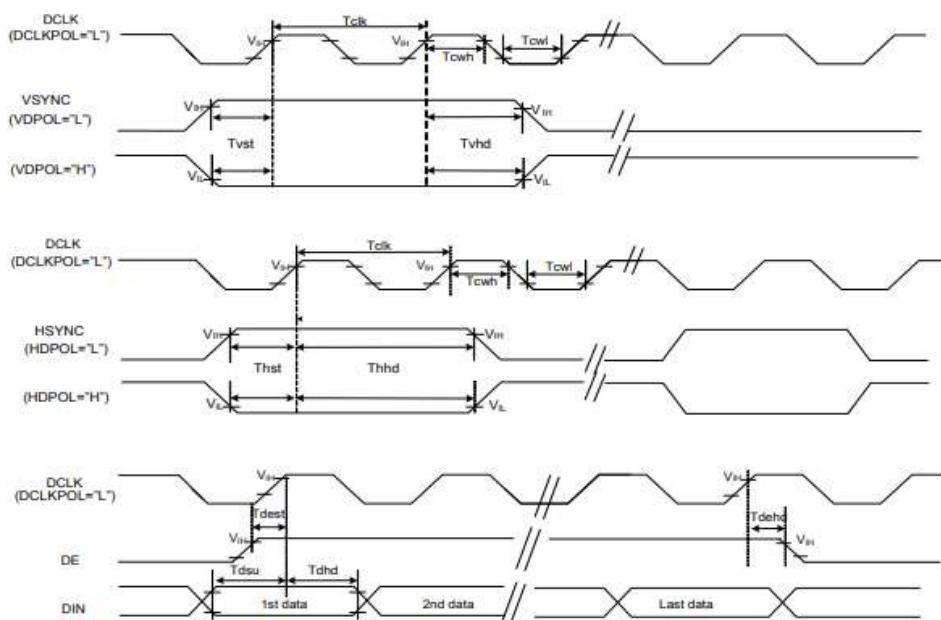
DC Electrical Characteristics (PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25°C, Bare Chip)

Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
VDD Power Source Slew Time	TPOR	-	-	20	ms	From 0V to 99% VDD
GRB Pulse Width	tRSTW	10	50	-	us	R=10Kohm, C=1uF
SD Output Stable Time	Tst	-	-	12	us	Output settled within +20mV Loading = 6.8k+28.2pF.
GD Output Rise and Fall Time	Tgst	-	-	6	us	Output settled (5%~95%), Loading = 4.7k+29.8pF

DCLK Negative Polarity (DCLKPOL="H")



DCLK Positive Polarity (DCLKPOL="L")



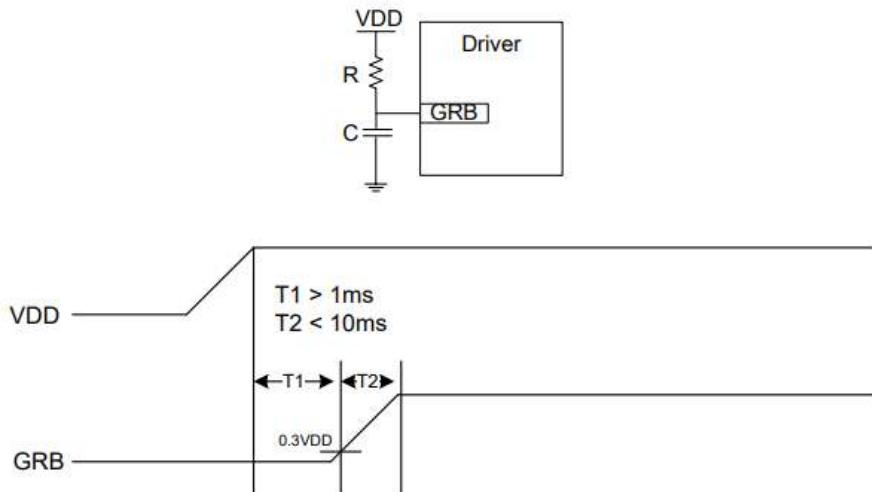
DC Electrical Characteristics (PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25°C, Bare Chip)

Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
CLK Pulse Duty	Tcw	40	50	60	%	
VSYNC Setup Time	Tvst	10	-	-	ns	
VSYNC Hold Time	Tvh	10	-	-	ns	
HSYNC Setup Time	Thst	10	-	-	ns	
HSYNC Hold Time	Thhd	10	-	-	ns	
Data Setup Time	Tdsu	10	-	-	ns	
Data Hold Time	Tdhd	10	-	-	ns	
DE Setup Time	Tdest	10	-	-	ns	
DE Hold Time	Tdehd	10	-	-	ns	

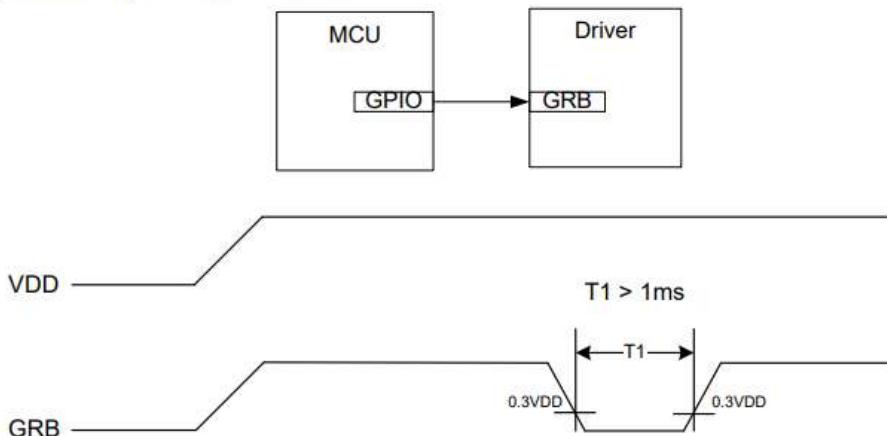
Reset timing

Setting GRB pin to "L" (hardware reset) can initialize internal function. Initialized by GRB pin is essential before operating. There are two suggestions for hardware reset connection.

(1) The GRB pin with external RC circuit.



(2) The GRB pin controlled by MCU.

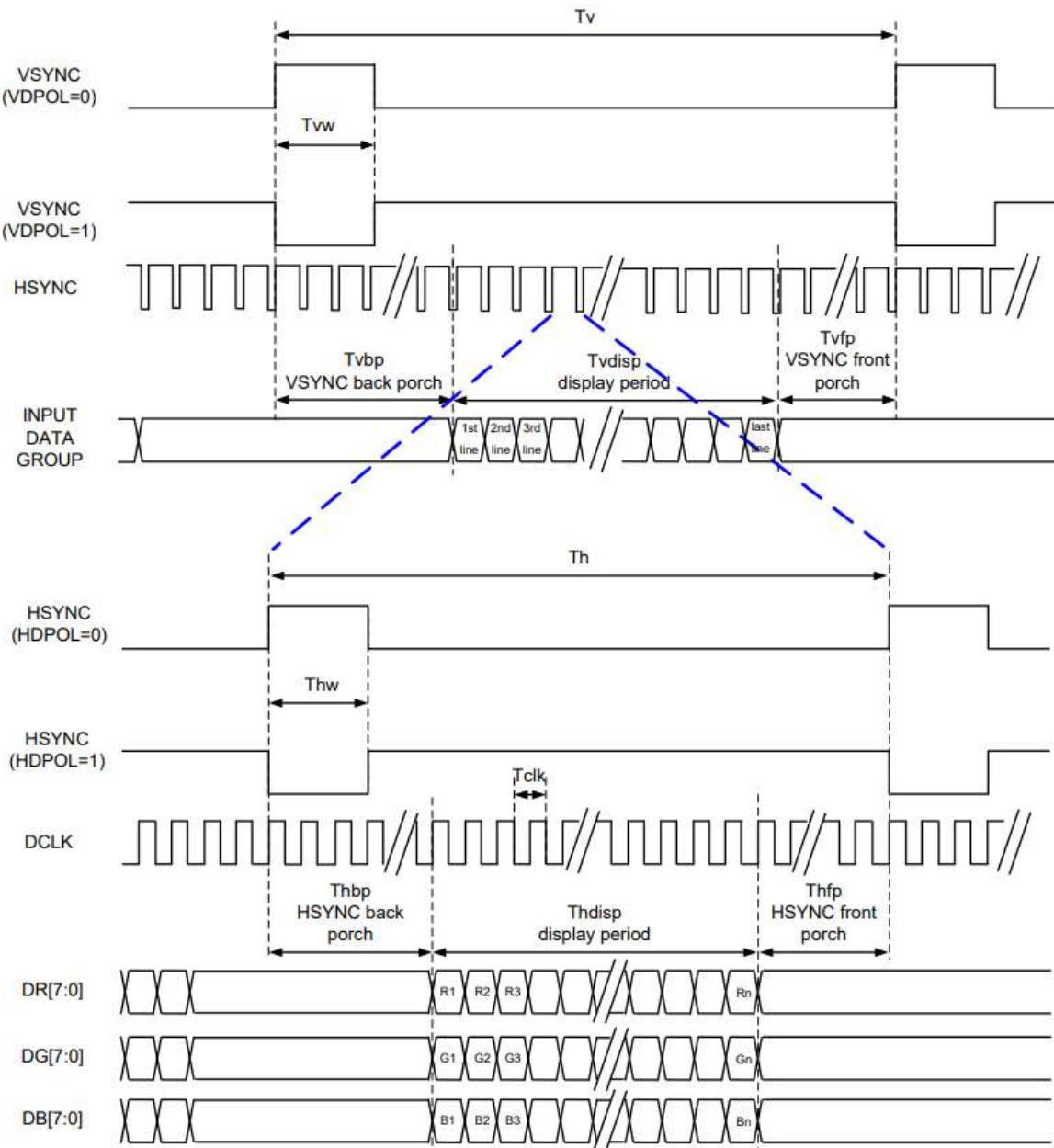


RGB Interface

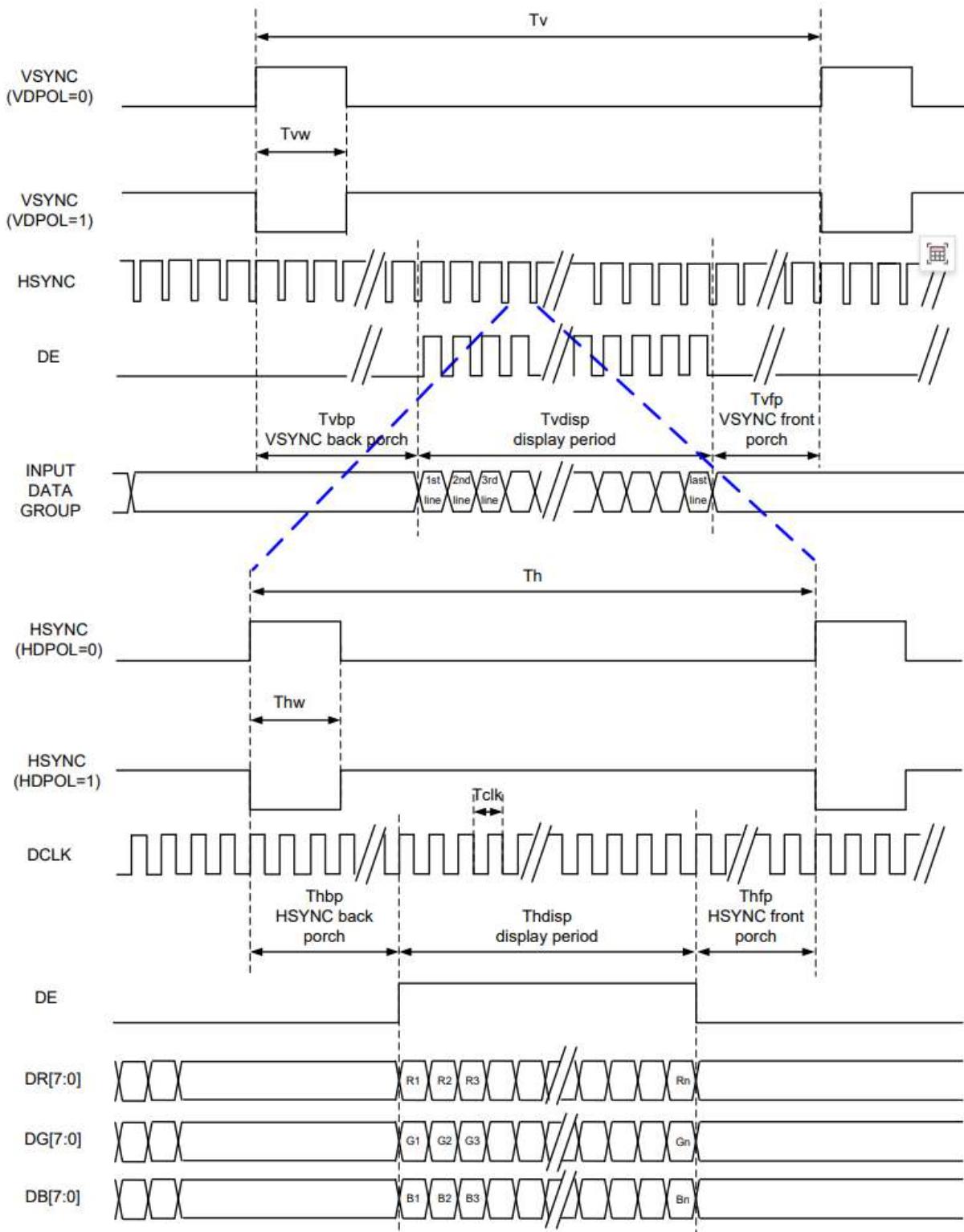
RGB Mode Selection Table	DCLK	Hsync	Vsync	DE
SYNC - DE Mode	Input	Input	Input	Input
SYNC Mode	Input	Input	Input	GND
DE Mode	Input	GND	GND	Input

Note: "Input" means these signals are driven by host side

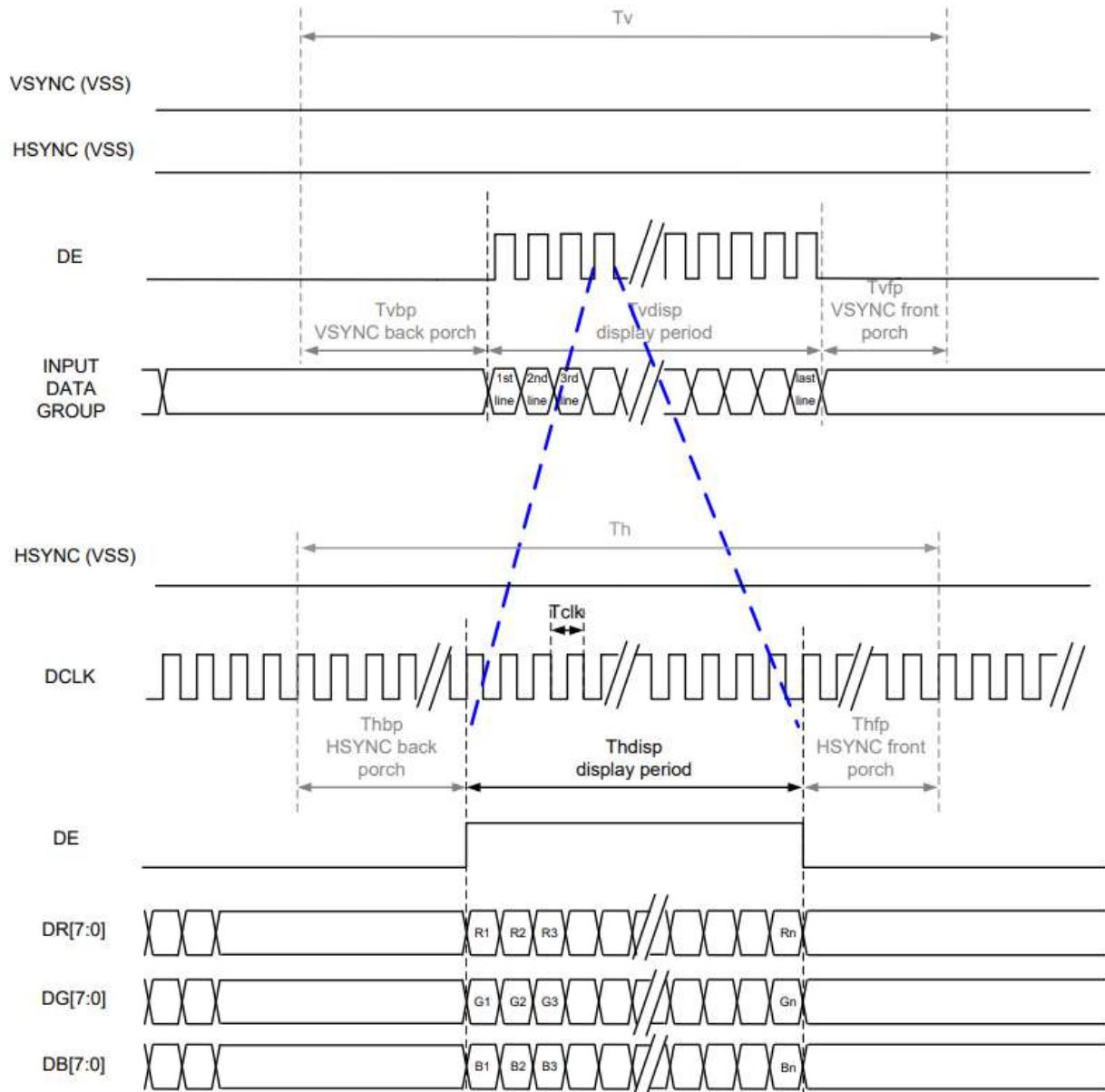
SYNC Mode



SYNC-DE Mode



DE Mode



Parallel 24-bit RGB Input Timing Table

Parallel 24-bit RGB Input Timing (PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25°C)

Parallel 24-bit RGB Interface Timing Table						
Item	Symbol	Min.	Typ.	Max.	Unit	Remark
DCLK Frequency	Fclk	23	25	27	MHz	
Hsync	Period Time	Th	808	816	848	DCLK
	Display Period	Thdisp	800			DCLK
	Back Porch	Thbp	4	8	24	DCLK
	Front Porch	Thfp	4	8	24	DCLK
	Pulse Width	Thw	2	4	8	DCLK
Vsync	Period Time	Tv	496	512	528	Hsync
	Display Period	Tvdisp	480			Hsync
	Back Porch	Tvbp	8	16	24	Hsync
	Front Porch	Tvfp	8	16	24	Hsync
	Pulse Width	Tvw	2	4	8	Hsync

Note: 1. The minimum blanking time depends on the GIP timing of the panel specification

2. To ensure the compatibility of different panels, it is recommended to use the typical setting.

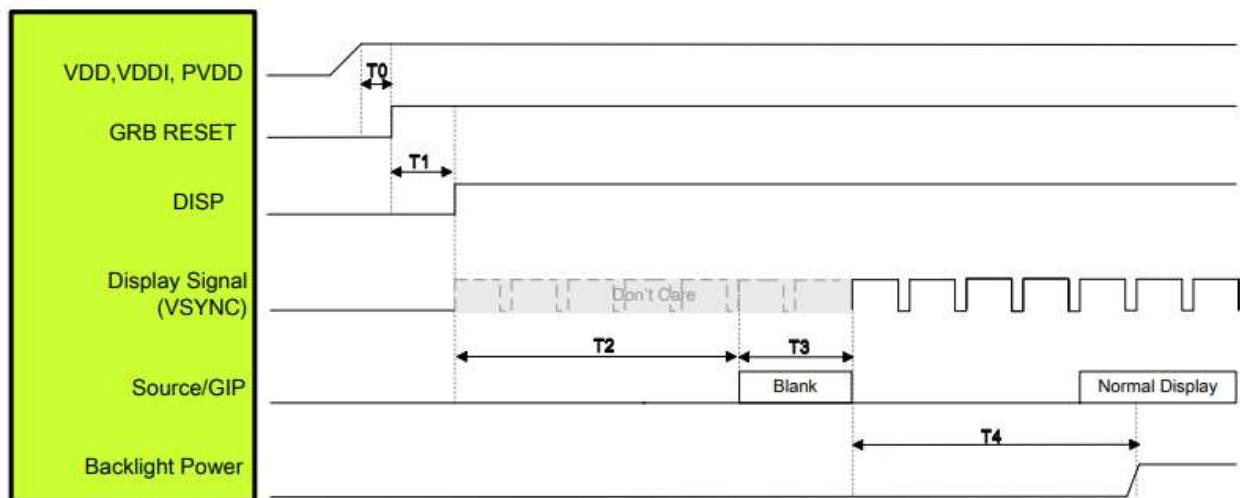
3. It is necessary to keep $Tvbp = 16$ and $Thbp = 8$ in sync mode. DE mode is unnecessary to keep it.

9. POWER SEQUENCE

To prevent the device damage from latch up and Improve subjective display effect, the power ON/OFF sequence shown below must be followed.

Power On Sequence

Power Mode



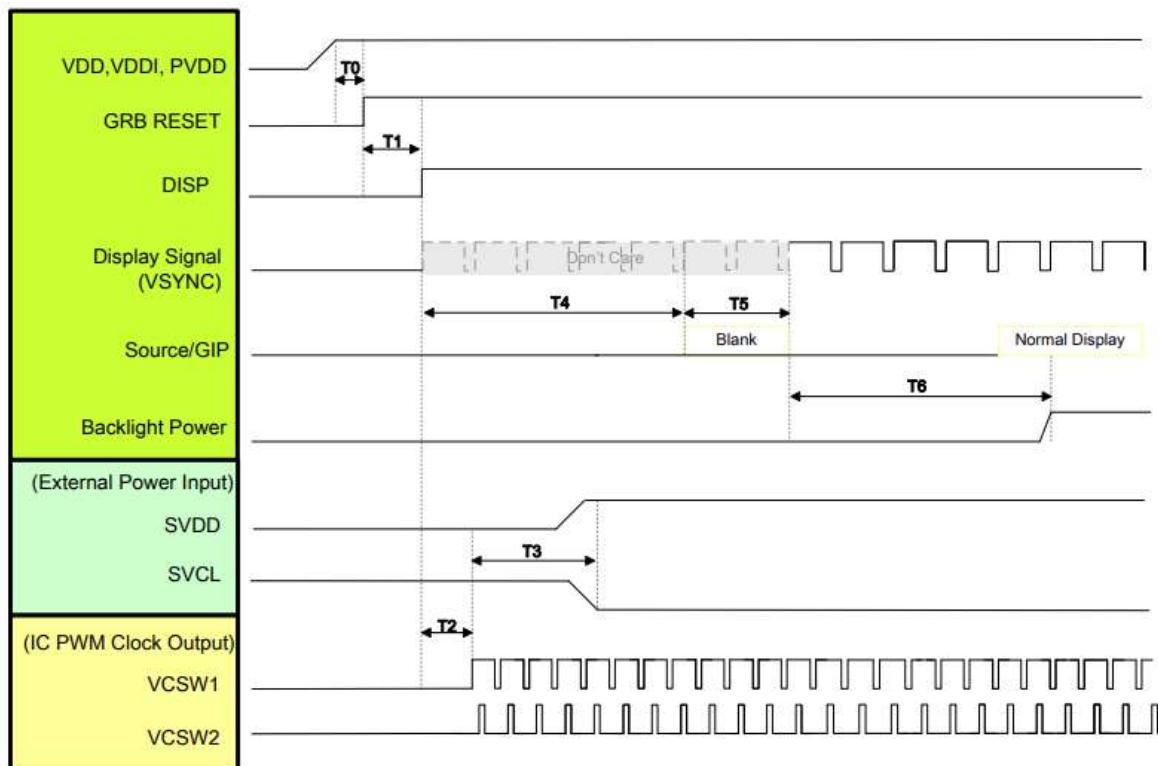
Symbol	Description	Time	Unit
T0	System power stability to GRB RESET signal	≥ 1	ms
T1	GRB RESET= "High" to DISP="High"	≥ 10	ms
T2	DISP="High" to Source/GIP scan blank	85	ms
T3	IC scan blanking signal	≥ 33	ms
T4	Display signal input to Backlight power on (base on Display Signal Frame Rate 60Hz)	≥ 100	ms

Note: 1. When DISP pull "H" or "L", IC will execute the internal power on or power off procedures .Please be careful about the timing of DISP and do not interrupt it during power on or power off procedure, otherwise unexpected errors will occur.

2. RGB interface Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0].

3. LVDS interface Display signal: DCLK P/N; RX[3:0] P/N

3 Power Mode with Charge Pump Controller



Symbol	Description	Time	Unit
T0	System power stability to GRB RESET signal	≥ 1	ms
T1	GRB RESET= "High" to DISP= "High"	≥ 10	ms
T2	DISP="High" to IC output PWM clock	1	ms
T3	PWM clock input to SVDD/SVCL stability	≤ 50	ms
T4	DISP="High" to Source/GIP scan blank	85	ms
T5	IC scan blanking signal	≥ 33	ms
T6	Display Signal input to Backlight power on (base on Display Signal Frame Rate 60Hz)	≥ 100	ms

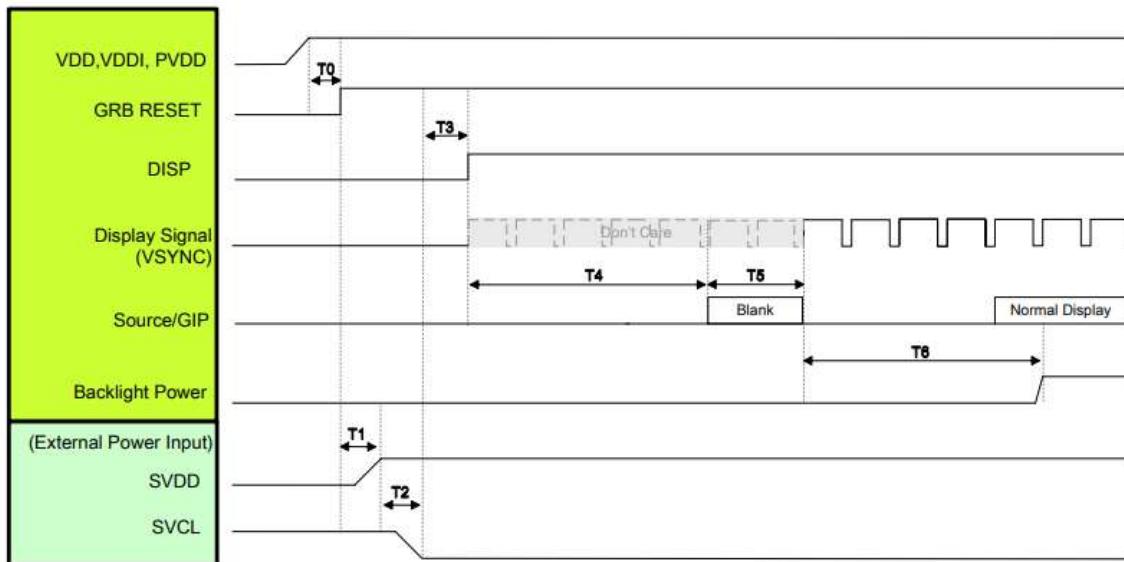
Note: 1. When DISP pull "H" or "L", IC will execute the internal power on or power off procedures .Please be careful about the timing of

DISP and do not interrupt it during power on or power off procedure, otherwise unexpected errors will occur.

2. RGB interface Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0].

3. LVDS interface Display signal: DCLK P/N; RX[3:0] P/N.

Power Mode with External Power Supply



Symbol	Description	Time	Unit
T0	System power stability to GRB RESET signal	≥ 1	ms
T1	GRB RESET= "High" to SVDD input	≥ 10	ms
T2	SVDD input to SVCL input	≥ 1	ms
T3	SVCL input to DISP="High"	≥ 1	ms
T4	DISP="High" to Source/GIP scan blank	85	ms
T5	IC scan blanking signal	≥ 33	ms
T6	Display Signal input to Backlight power on (base on Display Signal Frame Rate 60Hz)	≥ 100	ms

Note: 1. When DISP pull "H" or "L", IC will execute the internal power on or power off procedures .Please be careful about the timing of

DISP and do not interrupt it during power on or power off procedure, otherwise unexpected errors will occur.

2. RGB interface Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0].

3. LVDS interface Display signal: DCLK P/N; RX[3:0] P/N.

10. RELIABILITY TEST CONDITIONS

No.	Test item	Test condition		Inspection after test	
10.1	High temperature storage test	+80°C/240 hours		Inspection after 2~4hours storage at room temperature, the sample should not have following defects : 1. Current changing value before test and after test is 50% larger; 2. Function defect : Non-display, abnormal display, missing lines, Short lines, ITO corrosion; 3. Visual defect : Air bubble in the LCD, Seal leak, Glass crack.	
10.2	Low temperature storage test	-30°C/240 hours			
10.3	High temperature operating test	+70°C/120 hours			
10.4	Low temperature operating test	-20°C/120 hours			
10.5	Thermal Shock (non-operation)	-30°C ↔ +70°C/10cycles (30min.)(<30sec.) (30min.)			
10.6	High temperature high humidity test(operating)	+50°C*90% RH/120 hours			
10.7	Vibration test for Packaging	Frequency : 250 r/min Amplitude : 1 inch Time: 45min			
10.8	Drop test for Packaging	Drop direction: 1 corner/3 edges/6 sides 10 times			
		Packing weight(kg)	Drop height(cm)		
		<11	80±1.6		
		11≤G<21	60±1.2		
		21≤G<31	50±1.0		
		31≤G<40	40±0.8		
10.9	ESD test	Air discharge: ±8KV, 10times Contact discharge: ±6KV, 10times			
<p>Remark :</p> <ol style="list-style-type: none"> 1.The test samples should be applied to only one test item. 2.Sample size for each test item is 3~5pcs. 3.For High temperature high humidity test, Pure water(Resistance>10MΩ) should be used. 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part. 5.Failure judgment criterion: Basic specification, Electrical characteristic, Mechanical characteristic, Optical characteristic. 6.After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification. 					

11. INSPECTION CRITERION

Refer to 《Inspection Criterion for TFT Products-To customer》

12. HANDLING PRECAUTIONS

12.1 Mounting method

The TFT module consists of two thin glass plates with polarizers which easily be damaged. And since the module is so constructed as to be fixed by utilizing fitting holes in the printed circuit board. Extreme care should be needed when handling the TFT modules.

12.2 Caution of TFT module handling and cleaning

When cleaning the display surface, Use soft cloth with solvent [recommended below] and wipe lightly :

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent :

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated :

- Soldering flux
- Chlorine (Cl) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (Cl), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The TFT module use C-MOS LSI drivers, so we recommended that you :

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

12.4 Packing

Module employ TFT elements and must be treated as such.

- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity.

12.5 Caution for operation

- It is an indispensable condition to drive TFT module within the specified voltage limit since the higher voltage then the limit cause the shorter TFT module life.
- An electrochemical reaction due to direct current causes TFT module undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature TFT module how dark color in them. However those phenomena do not mean malfunction or out of order with TFT module, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
- Usage under the maximum operating temperature, 50%Rh or less is required.
- When fixed patterns are displayed for a long time, remnant image is likely to occur.

12.6 Storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storing in an ambient temperature $23\pm5^{\circ}\text{C}$, and in a relative humidity of $50\pm5\%$. Don't expose to sunlight or fluorescent light.
- Storing in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
- After stock for a long time, there may be residual glue when remove the protective film away, customer has to clean it before using.

It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

12.7 Safety

- It is recommendable to crash damaged or unnecessary TFT module into pieces and wash off liquid crystal by

either of solvents such as acetone and ethanol, which should be burned up later.

- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

13. PRECAUTION FOR USE

13.1 A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2 On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen which is not specified in this specifications.
- When an inspection specifications change or operating condition change in customer is reported to ODNA, and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. PACKING SPECIFICATION

Please consult our technical department for detail information.

15. INITIALIZATION CODE

Please consult our technical department for detail information.

16. HSF COMPLIANCE

- This products complies with ROHS 2011/65/EU and 2015/863/EU, REACH 1907/2006/EC requirements, and the packaging complies with 94-62-EC.